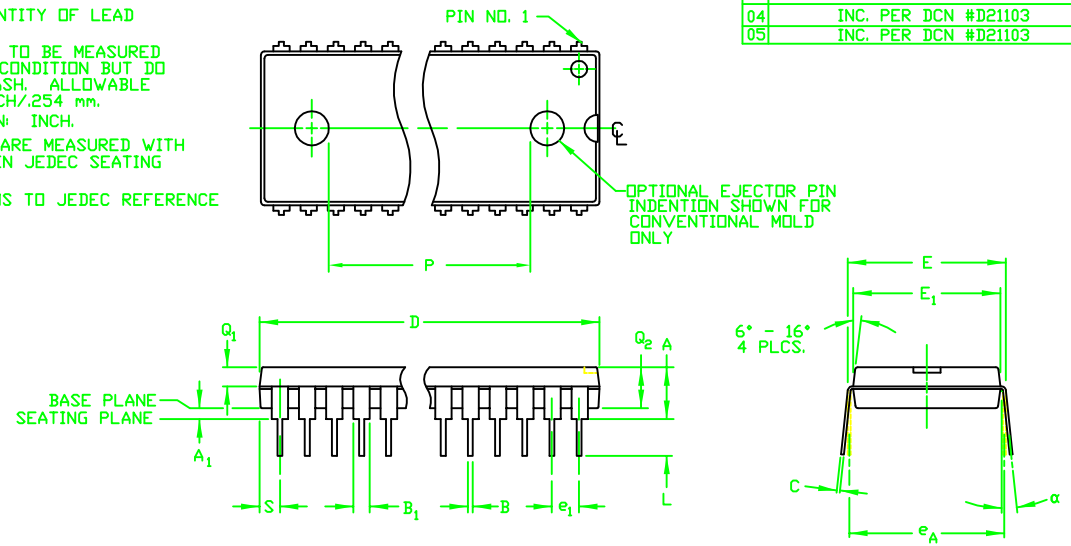
NOTES:

1. REFER TO APPLICABLE SYMBOL LIST.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5-1982.
3. α APPLIES TO SPREAD LEADS PRIOR TO INSTALLATION.
4. N IS THE MAXIMUM QUANTITY OF LEAD POSITIONS.
5. DIMENSION D & E ARE TO BE MEASURED AT MAXIMUM MATERIAL CONDITION BUT DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS .010 INCH/.254 mm.
6. CONTROLLING DIMENSION: INCH.
7. DIMENSIONS A, A_1, & L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
8. THIS PACKAGE CONFORMS TO JEDEC REFERENCE MS-011, VARIATION AA.

REV.	DESCRIPTION	DATE	ORIGINATOR
00	INITIAL RELEASE.	8/5 1987	Y.M.K
01	INC. PER DCN #A30968.	8/27 1988	H.J.C
02	INC. PER DCN #A32097.	2/16 1990	H.J.C
03	INC. PER DCN #A32675.	7/25 1990	H.J.C
04	INC. PER DCN #D21103	2/28 1992	Y.M.K
05	INC. PER DCN #D21103	4/17 1996	T.Y.L.



DECIMAL ANGULAR XX± ± XXX± XXXX±	PROJECTION		
MATERIAL	APPROVALS	DATE	
FINISH	DRAWN MCERENO	4/26 1995	
DO NOT SCALE DRAWING	CHECKED RALBO	4/26 1995	
	ENGR LCANDY	4/26 1995	
	RELEASED TLLORENTE	4/17 1996	

Anam Industrial Co., LTD. Seoul, Korea
Amkor Electronics Irving, TX
Amkor/Anam Philipines, INC. Manila, Philippines
Amkor Electronics Chandler, AZ

anam amkor EXCELLENCE IN SEMICONDUCTOR ASSEMBLY AND TEST

TITLE: PACKAGE OUTLINE, 24 LEAD, P-DIP, .600 INCH, FULL LEAD, AAWW

SIZE	DWG. NO.	REV.
B	00289	05

SCALE 3/1 SHEET 1 of 2